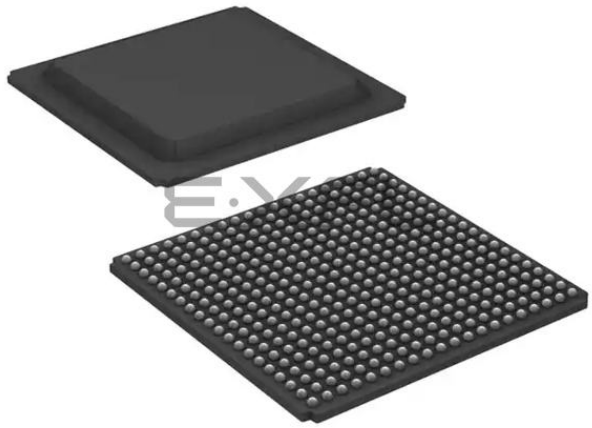

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	896
Number of Logic Elements/Cells	8064
Total RAM Bits	368640
Number of I/O	311
Number of Gates	400000
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	400-BGA
Supplier Device Package	400-FBGA (21x21)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc3s400an-4fg400c

- Sector-based data protection and security features
  - Sector Protect: Write- and erase-protect a sector (changeable)
  - Sector Lockdown: Sector data is unchangeable (permanent)
- 128-byte Security Register
  - Separate from FPGA's unique Device DNA identifier
  - 64-byte factory-programmed identifier unique to the in-system Flash memory
  - 64-byte one-time programmable, user-programmable field
- 100,000 Program/Erase cycles
- 20-year data retention
- Comprehensive programming support
  - In-system prototype programming via JTAG using Xilinx Platform Cable USB and iMPACT software
  - Product programming support using BPM Microsystems programmers with appropriate programming adapter
  - Design examples demonstrating in-system programming from a Spartan-3AN FPGA application

I/O Capabilities

The Spartan-3AN FPGA SelectIO interface supports many popular single-ended and differential standards. Table 4 shows the number of user I/Os as well as the number of differential I/O pairs available for each device/package combination. Some of the user I/Os are unidirectional, input-only pins as indicated in Table 4.

Spartan-3AN FPGAs support the following single-ended standards:

- 3.3V low-voltage TTL (LVTTL)
- Low-voltage CMOS (LVCMOS) at 3.3V, 2.5V, 1.8V, 1.5V, or 1.2V
- 3.3V PCI at 33 MHz or 66 MHz
- HSTL I, II, and III at 1.5V and 1.8V, commonly used in memory applications
- SSTL I and II at 1.8V, 2.5V, and 3.3V, commonly used for memory applications

Spartan-3AN FPGAs support the following differential standards:

- LVDS, mini-LVDS, RSDS, and PPDS I/O at 2.5V or 3.3V
- Bus LVDS I/O at 2.5V
- TMDS I/O at 3.3V
- Differential HSTL and SSTL I/O
- LVPECL inputs at 2.5V or 3.3V

Table 4: **Available User I/Os and Differential (Diff) I/O Pairs**

Package(1)	**TQ144 TQG144**		**FT256 FTG256**		**FG400 FGG400**		**FG484 FGG484**		**FG676 FGG676**	
Body Size (mm)	**20 x 20**(2)		**17 x 17**		**21 x 21**		**23 x 23**		**27 x 27**	
Device(3)	**User**	**Diff**	**User**	**Diff**	**User**	**Diff**	**User**	**Diff**	**User**	**Diff**
XC3S50AN	**108**(4) *(7)*	**50** *(24)*	**144** *(32)*	**64** *(32)*	–	–	–	–	–	–
XC3S200AN	–	–	**195** *(35)*	**90** *(50)*	–	–	–	–	–	–
XC3S400AN	–	–	**195** *(35)*	**90** *(50)*	**311** *(63)*	**142** *(78)*	–	–	–	–
XC3S700AN	–	–	–	–	–	–	**372** *(84)*	**165** *(93)*	–	–
XC3S1400AN	–	–	–	–	–	–	**375** *(87)*	**165** *(93)*	**502** *(94)*	**227** *(131)*

Notes:

1. See Pb and Pb-Free Packaging, page 7 for details on Pb and Pb-free packaging options.
2. The footprint for the TQ(G)144 (22 mm x 22 mm) package is larger than the package body.
3. Each Spartan-3AN FPGA has a pin-compatible Spartan-3A FPGA equivalent, although Spartan-3A FPGAs do not have internal SPI flash and offer more part/package combinations.
4. The number shown in **bold** indicates the maximum number of I/O and input-only pins. The number shown in (*italics*) indicates the number of input-only pins. The differential (Diff) input-only pin count includes both differential pairs on input-only pins and differential pairs on I/O pins within I/O banks that are restricted to differential inputs.

Table 14: **DC Characteristics of User I/Os Using Single-Ended Standards**

IOSTANDARD Attribute		Test Conditions		Logic Level Characteristics	
		I_{OL} (mA)	I_{OH} (mA)	V_{OL} Max (V)	V_{OH} Min (V)
LVTTL(3)	2	2	–2	0.4	2.4
	4	4	–4		
	6	6	–6		
	8	8	–8		
	12	12	–12		
	16	16	–16		
	24	24	–24		
LVCMOS33(3)	2	2	–2	0.4	V_{CCO} – 0.4
	4	4	–4		
	6	6	–6		
	8	8	–8		
	12	12	–12		
	16	16	–16		
	24(5)	24	–24		
LVCMOS25(3)	2	2	–2	0.4	V_{CCO} – 0.4
	4	4	–4		
	6	6	–6		
	8	8	–8		
	12	12	–12		
	16(5)	16	–16		
	24(5)	24	–24		
LVCMOS18(3)	2	2	–2	0.4	V_{CCO} – 0.4
	4	4	–4		
	6	6	–6		
	8	8	–8		
	12(5)	12	–12		
	16(5)	16	–16		
LVCMOS15(3)	2	2	–2	0.4	V_{CCO} – 0.4
	4	4	–4		
	6	6	–6		
	8(5)	8	–8		
	12(5)	12	–12		
LVCMOS12(3)	2	2	–2	0.4	V_{CCO} – 0.4
	4(5)	4	–4		
	6(5)	6	–6		
PCI33_3(4)		1.5	–0.5	10% V_{CCO}	90% V_{CCO}
PCI66_3(4)		1.5	–0.5	10% V_{CCO}	90% V_{CCO}

Table 14: **DC Characteristics of User I/Os Using Single-Ended Standards *(Cont'd)***

IOSTANDARD Attribute	Test Conditions		Logic Level Characteristics	
	I_{OL} (mA)	I_{OH} (mA)	V_{OL} Max (V)	V_{OH} Min (V)
HSTL_I(5)	8	–8	0.4	V_{CCO} - 0.4
HSTL_III(5)	24	–8	0.4	V_{CCO} - 0.4
HSTL_I_18	8	–8	0.4	V_{CCO} - 0.4
HSTL_II_18(5)	16	–16	0.4	V_{CCO} - 0.4
HSTL_III_18	24	–8	0.4	V_{CCO} - 0.4
SSTL18_I	6.7	–6.7	V_{TT} – 0.475	V_{TT} + 0.475
SSTL18_II(5)	13.4	–13.4	V_{TT} – 0.603	V_{TT} + 0.603
SSTL2_I	8.1	–8.1	V_{TT} – 0.61	V_{TT} + 0.61
SSTL2_II(5)	16.2	–16.2	V_{TT} – 0.81	V_{TT} + 0.81
SSTL3_I	8	–8	V_{TT} – 0.6	V_{TT} + 0.6
SSTL3_II	16	–16	V_{TT} – 0.8	V_{TT} + 0.8

Notes:

1. The numbers in this table are based on the conditions set forth in Table 10 and Table 13.
2. Descriptions of the symbols used in this table are as follows:
   I_{OL} — the output current condition under which V_{OL} is tested
   I_{OH} — the output current condition under which V_{OH} is tested
   V_{OL} — the output voltage that indicates a Low logic level
   V_{OH} — the output voltage that indicates a High logic level
   V_{CCO} — the supply voltage for output drivers
   V_{TT} — the voltage applied to a resistor termination
3. For the LVCMOS and LVTTL standards: the same V_{OL} and V_{OH} limits apply for the Fast, Slow and QUIETIO slew attributes.
4. Tested according to the relevant PCI specifications. For information on PCI IP solutions, see www.xilinx.com/products/design_resources/conn_central/protocols/pci_pcix.htm. The PCIX IOSTANDARD is available and has equivalent characteristics but no PCI-X IP is supported.
5. These higher-drive output standards are supported only on FPGA banks 1 and 3. Inputs are unrestricted. See the chapter "Using I/O Resources" in UG331.

Input Setup and Hold Times

Table 23: **Setup and Hold Times for the IOB Input Path**

Symbol	Description	Conditions	IFD_DELAY_VALUE	Device	Speed Grade		Units
					-5	-4	
					Min	Min	
Setup Times							
T_{IOPICK}	Time from the setup of data at the Input pin to the active transition at the ICLK input of the Input Flip-Flop (IFF). No Input Delay is programmed.	LVCMOS25[2]	0	XC3S50AN	1.56	1.58	ns
				XC3S200AN	1.71	1.81	ns
				XC3S400AN	1.30	1.51	ns
				XC3S700AN	1.34	1.51	ns
				XC3S1400AN	1.36	1.74	ns
$T_{IOPICKD}$	Time from the setup of data at the Input pin to the active transition at the ICLK input of the Input Flip-Flop (IFF). The Input Delay is programmed.	LVCMOS25[2]	1	XC3S50AN	2.16	2.18	ns
			2		3.10	3.12	ns
			3		3.51	3.76	ns
			4		4.04	4.32	ns
			5		3.88	4.24	ns
			6		4.72	5.09	ns
			7		5.47	5.94	ns
			8		5.97	6.52	ns
			1	XC3S200AN	2.05	2.20	ns
			2		2.72	2.93	ns
			3		3.38	3.78	ns
			4		3.88	4.37	ns
			5		3.69	4.20	ns
			6		4.56	5.23	ns
			7		5.34	6.11	ns
			8		5.85	6.71	ns
			1	XC3S400AN	1.79	2.02	ns
			2		2.43	2.67	ns
			3		3.02	3.43	ns
			4		3.49	3.96	ns
			5		3.41	3.95	ns
			6		4.20	4.81	ns
			7		4.96	5.66	ns
			8		5.44	6.19	ns

Input Timing Adjustments

Table 26: **Input Timing Adjustments by IOSTANDARD**

Convert Input Time from LVCMOS25 to the Following Signal Standard (IOSTANDARD)	Add the Adjustment Below		Units
	Speed Grade		
	-5	-4	
Single-Ended Standards			
LVTTL	0.62	0.62	ns
LVCMOS33	0.54	0.54	ns
LVCMOS25	0	0	ns
LVCMOS18	0.83	0.83	ns
LVCMOS15	0.60	0.60	ns
LVCMOS12	0.31	0.31	ns
PCI33_3	0.41	0.41	ns
PCI66_3	0.41	0.41	ns
HSTL_I	0.72	0.72	ns
HSTL_III	0.77	0.77	ns
HSTL_I_18	0.69	0.69	ns
HSTL_II_18	0.69	0.69	ns
HSTL_III_18	0.79	0.79	ns
SSTL18_I	0.71	0.71	ns
SSTL18_II	0.71	0.71	ns
SSTL2_I	0.68	0.68	ns
SSTL2_II	0.68	0.68	ns
SSTL3_I	0.78	0.78	ns
SSTL3_II	0.78	0.78	ns

Table 26: **Input Timing Adjustments by IOSTANDARD**

Convert Input Time from LVCMOS25 to the Following Signal Standard (IOSTANDARD)	Add the Adjustment Below		Units
	Speed Grade		
	-5	-4	
Differential Standards			
LVDS_25	0.76	0.76	ns
LVDS_33	0.79	0.79	ns
BLVDS_25	0.79	0.79	ns
MINI_LVDS_25	0.78	0.78	ns
MINI_LVDS_33	0.79	0.79	ns
LVPECL_25	0.78	0.78	ns
LVPECL_33	0.79	0.79	ns
RSDS_25	0.79	0.79	ns
RSDS_33	0.77	0.77	ns
TMDS_33	0.79	0.79	ns
PPDS_25	0.79	0.79	ns
PPDS_33	0.79	0.79	ns
DIFF_HSTL_I_18	0.74	0.74	ns
DIFF_HSTL_II_18	0.72	0.72	ns
DIFF_HSTL_III_18	1.05	1.05	ns
DIFF_HSTL_I	0.72	0.72	ns
DIFF_HSTL_III	1.05	1.05	ns
DIFF_SSTL18_I	0.71	0.71	ns
DIFF_SSTL18_II	0.71	0.71	ns
DIFF_SSTL2_I	0.74	0.74	ns
DIFF_SSTL2_II	0.75	0.75	ns
DIFF_SSTL3_I	1.06	1.06	ns
DIFF_SSTL3_II	1.06	1.06	ns

Notes:

1. The numbers in this table are tested using the methodology presented in Table 30 and are based on the operating conditions set forth in Table 10, Table 13, and Table 15.
2. These adjustments are used to convert input path times originally specified for the LVCMOS25 standard to times that correspond to other signal standards.

Table 32: **Recommended Number of Simultaneously Switching Outputs per V_{CCO}-GND Pair**

Signal Standard (IOSTANDARD)			Package Type			
			TQG144		FTG256, FGG400, FGG484, FGG676	
			Top, Bottom Banks 0,2	Left, Right Banks 1,3	Top, Bottom Banks 0,2	Left, Right Banks 1,3
Single-Ended Standards						
LVTTL	Slow	2	20	20	60	60
		4	10	10	41	41
		6	10	10	29	29
		8	6	6	22	22
		12	6	6	13	13
		16	5	5	11	11
		24	4	4	9	9
	Fast	2	10	10	10	10
		4	6	6	6	6
		6	5	5	5	5
		8	3	3	3	3
		12	3	3	3	3
		16	3	3	3	3
		24	2	2	2	2
	QuietIO	2	40	40	80	80
		4	24	24	48	48
		6	20	20	36	36
		8	16	16	27	27
		12	12	12	16	16
		16	9	9	13	13
		24	9	9	12	12

Table 32: **Recommended Number of Simultaneously Switching Outputs per V_{CCO}-GND Pair *(Cont'd)***

Signal Standard (IOSTANDARD)			Package Type			
			TQG144		FTG256, FGG400, FGG484, FGG676	
			Top, Bottom Banks 0,2	Left, Right Banks 1,3	Top, Bottom Banks 0,2	Left, Right Banks 1,3
LVCMOS33	Slow	2	24	24	76	76
		4	14	14	46	46
		6	11	11	27	27
		8	10	10	20	20
		12	9	9	13	13
		16	8	8	10	10
		24	–	8	–	9
	Fast	2	10	10	10	10
		4	8	8	8	8
		6	5	5	5	5
		8	4	4	4	4
		12	4	4	4	4
		16	2	2	2	2
		24	–	2	–	2
	QuietIO	2	36	36	76	76
		4	32	32	46	46
		6	24	24	32	32
		8	16	16	26	26
		12	16	16	18	18
		16	12	12	14	14
		24	–	10	–	10

Table 34: **CLB Distributed RAM Switching Characteristics**

Symbol	Description	Speed Grade				Units
		-5		-4		
		Min	Max	Min	Max	
Clock-to-Output Times						
T_{SHCKO}	Time from the active edge at the CLK input to data appearing on the distributed RAM output	–	1.69	–	2.01	ns
Setup Times						
T_{DS}	Setup time of data at the BX or BY input before the active transition at the CLK input of the distributed RAM	–0.07	–	–0.02	–	ns
T_{AS}	Setup time of the F/G address inputs before the active transition at the CLK input of the distributed RAM	0.18	–	0.36	–	ns
T_{WS}	Setup time of the write enable input before the active transition at the CLK input of the distributed RAM	0.30	–	0.59	–	ns
Hold Times						
T_{DH}	Hold time of the BX and BY data inputs after the active transition at the CLK input of the distributed RAM	0.13	–	0.13	–	ns
T_{AH}, T_{WH}	Hold time of the F/G address inputs or the write enable input after the active transition at the CLK input of the distributed RAM	0.01	–	0.01	–	ns
Clock Pulse Width						
T_{WPH}, T_{WPL}	Minimum High or Low pulse width at CLK input	0.88	–	1.01	–	ns

Notes:

1. The numbers in this table are based on the operating conditions set forth in Table 10.

Table 35: **CLB Shift Register Switching Characteristics**

Symbol	Description	Speed Grade				Units
		-5		-4		
		Min	Max	Min	Max	
Clock-to-Output Times						
T_{REG}	Time from the active edge at the CLK input to data appearing on the shift register output	–	4.11	–	4.82	ns
Setup Times						
T_{SRLDS}	Setup time of data at the BX or BY input before the active transition at the CLK input of the shift register	0.13	–	0.18	–	ns
Hold Times						
T_{SRLDH}	Hold time of the BX or BY data input after the active transition at the CLK input of the shift register	0.16	–	0.16	–	ns
Clock Pulse Width						
T_{WPH}, T_{WPL}	Minimum High or Low pulse width at CLK input	0.90	–	1.01	–	ns

Notes:

1. The numbers in this table are based on the operating conditions set forth in Table 10.

Clock Buffer/Multiplexer Switching Characteristics

Table 36: **Clock Distribution Switching Characteristics**

Description	Symbol	Minimum	Maximum		Units
			Speed Grade		
			-5	-4	
Global clock buffer (BUFG, BUFGMUX, BUFGCE) I input to O-output delay	T_{GIO}	–	0.22	0.23	ns
Global clock multiplexer (BUFGMUX) select S-input setup to I0 and I1 inputs. Same as BUFGCE enable CE-input	T_{GSI}	–	0.56	0.63	ns
Frequency of signals distributed on global buffers (all sides)	F_{BUFG}	0	350	334	MHz

Notes:

1. The numbers in this table are based on the operating conditions set forth in Table 10.

DNA Port Timing

Table 46: **DNA_PORT Interface Timing**

Symbol	Description	Min	Max	Units
T_{DNASSU}	Setup time on SHIFT before the rising edge of CLK	1.0	–	ns
T_{DNASH}	Hold time on SHIFT after the rising edge of CLK	0.5	–	ns
T_{DNADSU}	Setup time on DIN before the rising edge of CLK	1.0	–	ns
T_{DNADH}	Hold time on DIN after the rising edge of CLK	0.5	–	ns
T_{DNARSU}	Setup time on READ before the rising edge of CLK	5.0	10,000	ns
T_{DNARH}	Hold time on READ after the rising edge of CLK	0	–	ns
$T_{DNADCKO}$	Clock-to-output delay on DOUT after rising edge of CLK	0.5	1.5	ns
$T_{DNACLKF}$	CLK frequency	0	100	MHz
$T_{DNACLKH}$	CLK High time	1.0	∞	ns
$T_{DNACLKL}$	CLK Low time	1.0	∞	ns

Notes:

1. The minimum READ pulse width is 5 ns, the maximum READ pulse width is 10 µs.

Internal SPI Access Port Timing

Table 47: **SPI_ACCESS Interface Timing**

Symbol	Description	Speed Grade				Units
		-5		-4		
		Min	Max	Min	Max	
T_{SPICCK_MOSI}	Setup time on MOSI before the active edge of CLK	4.47	–	5.0	–	ns
T_{SPICKC_MOSI}	Hold time on MOSI after the active edge of CLK	4.03	–	4.5	–	ns
T_{CSB}	CSB High time	50	–	50	–	ns
T_{SPICCK_CSB}	Setup time on CSB before the active edge of CLK	7.15	–	8.0	–	ns
T_{SPICCK_CSB}	Hold time on CSB after the active edge of CLK	7.15	–	8.0	–	ns
T_{SPICKO_MISO}	Clock-to-output delay on MISO after active edge of CLK	–	14.3	–	16.0	ns
F_{SPICLK}	CLK frequency	–	50	–	50	MHz
$F_{SPICAR1}$	CLK frequency for Continuous Array Read command	–	50	–	50	MHz
$F_{SPICAR1}$	CLK frequency for Continuous Array Read command, reduced initial latency	–	33	–	33	MHz
$T_{SPICLKL}$	CLK High time	–	∞	–	∞	ns
$T_{SPICLKH}$	CLK Low time	6.8	∞	6.8	∞	ns

Notes:

1. For details on using SPI_ACCESS and the In-System Flash memory, see UG333 *Spartan-3AN FPGA In-System Flash User Guide*.

Configuration Clock (CCLK) Characteristics

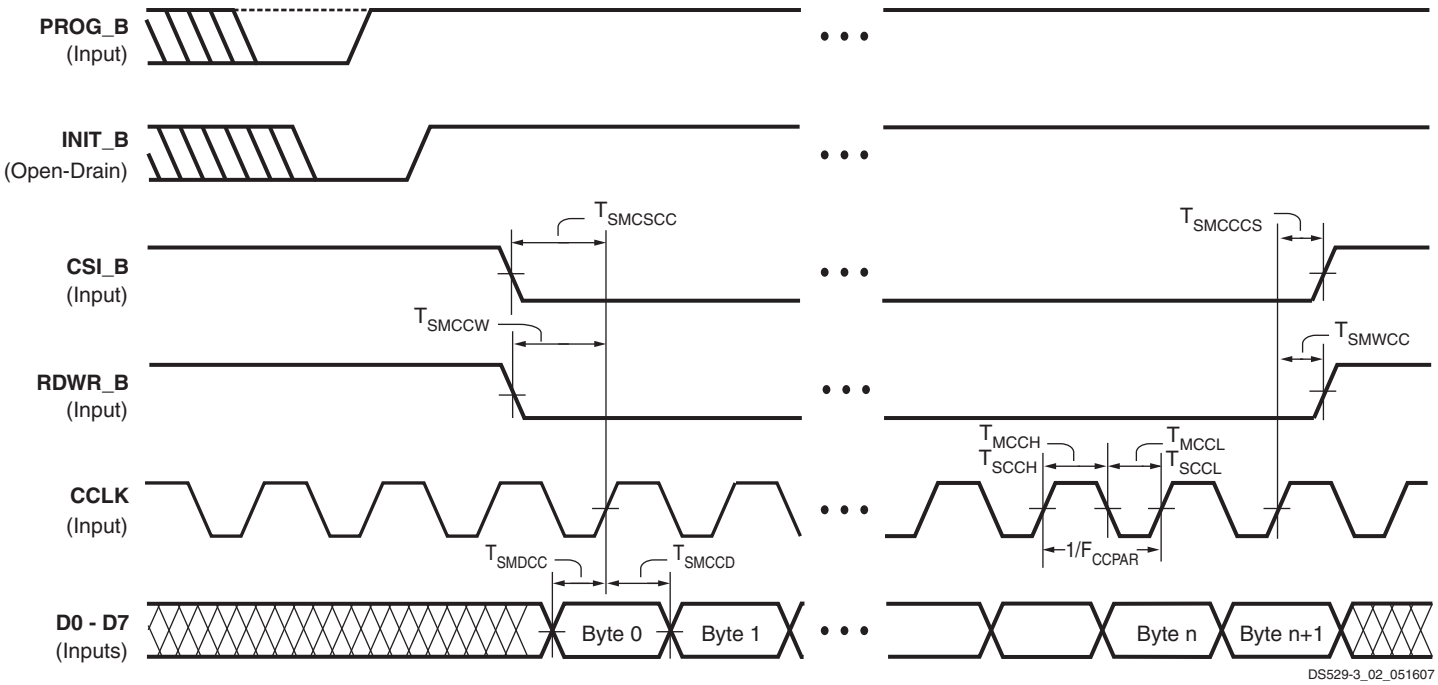
Table 51: **Master Mode CCLK Output Period by *ConfigRate* Option Setting**

Symbol	Description	*ConfigRate* Setting[1]	Temperature Range	Minimum	Maximum	Units
T_{CCLK1}	CCLK clock period by ***ConfigRate*** setting	1 *(power-on value)*	Commercial	1,254	2,500	ns
			Industrial	1,180		ns
T_{CCLK3}		3	Commercial	413	833	ns
			Industrial	390		ns
T_{CCLK6}		6 (*default*)	Commercial	207	417	ns
			Industrial	195		ns
T_{CCLK7}		7	Commercial	178	357	ns
			Industrial	168		ns
T_{CCLK8}		8	Commercial	156	313	ns
			Industrial	147		ns
T_{CCLK10}		10	Commercial	123	250	ns
			Industrial	116		ns
T_{CCLK12}		12	Commercial	103	208	ns
			Industrial	97		ns
T_{CCLK13}		13	Commercial	93	192	ns
			Industrial	88		ns
T_{CCLK17}		17	Commercial	72	147	ns
			Industrial	68		ns
T_{CCLK22}		22	Commercial	54	114	ns
			Industrial	51		ns
T_{CCLK25}		25	Commercial	47	100	ns
			Industrial	45		ns
T_{CCLK27}		27	Commercial	44	93	ns
			Industrial	42		ns
T_{CCLK33}		33	Commercial	36	76	ns
			Industrial	34		ns
T_{CCLK44}		44	Commercial	26	57	ns
			Industrial	25		ns
T_{CCLK50}		50	Commercial	22	50	ns
			Industrial	21		ns
$T_{CCLK100}$		100	Commercial	11.2	25	ns
			Industrial	10.6		ns

Notes:

1. Set the ***ConfigRate*** option value when generating a configuration bitstream.

Slave Parallel Mode Timing



Notes:

1. It is possible to abort configuration by pulling CSI_B Low in a given CCLK cycle, then switching RDWR_B Low or High in any subsequent cycle for which CSI_B remains Low. The RDWR_B pin asynchronously controls the driver impedance of the D0–D7 bus. When RDWR_B switches High, be careful to avoid contention on the D0–D7 bus.
2. To pause configuration, pause CCLK instead of de-asserting CSI_B. See UG332, Chapter 7, section “Non-Continuous SelectMAP Data Loading” for more details.

Figure 15: **Waveforms for Slave Parallel Configuration**

Table 56: **Timing for the Slave Parallel Configuration Mode**

Symbol	Description		All Speed Grades		Units
			Min	Max	
Setup Times					
T_{SMDCC}	The time from the setup of data at the D0-D7 pins to the rising transition at the CCLK pin		7	–	ns
T_{SMCSCC}	Setup time on the CSI_B pin before the rising transition at the CCLK pin		7	–	ns
T_{SMCCW}(2)	Setup time on the RDWR_B pin before the rising transition at the CCLK pin		15	–	ns
Hold Times					
T_{SMCCD}	The time from the rising transition at the CCLK pin to the point when data is last held at the D0-D7 pins		1.0	–	ns
T_{SMCCCS}	The time from the rising transition at the CCLK pin to the point when a logic level is last held at the CSO_B pin		0	–	ns
T_{SMWCC}	The time from the rising transition at the CCLK pin to the point when a logic level is last held at the RDWR_B pin		0	–	ns
Clock Timing					
T_{CCH}	The High pulse width at the CCLK input pin		5	–	ns
T_{CCL}	The Low pulse width at the CCLK input pin		5	–	ns
F_{CCPAR}	Frequency of the clock signal at the CCLK input pin	No bitstream compression	0	80	MHz
		With bitstream compression	0	80	MHz

Notes:

1. The numbers in this table are based on the operating conditions set forth in Table 10.
2. Some Xilinx documents refer to Parallel modes as SelectMAP modes.

External Serial Peripheral Interface (SPI) Configuration Timing

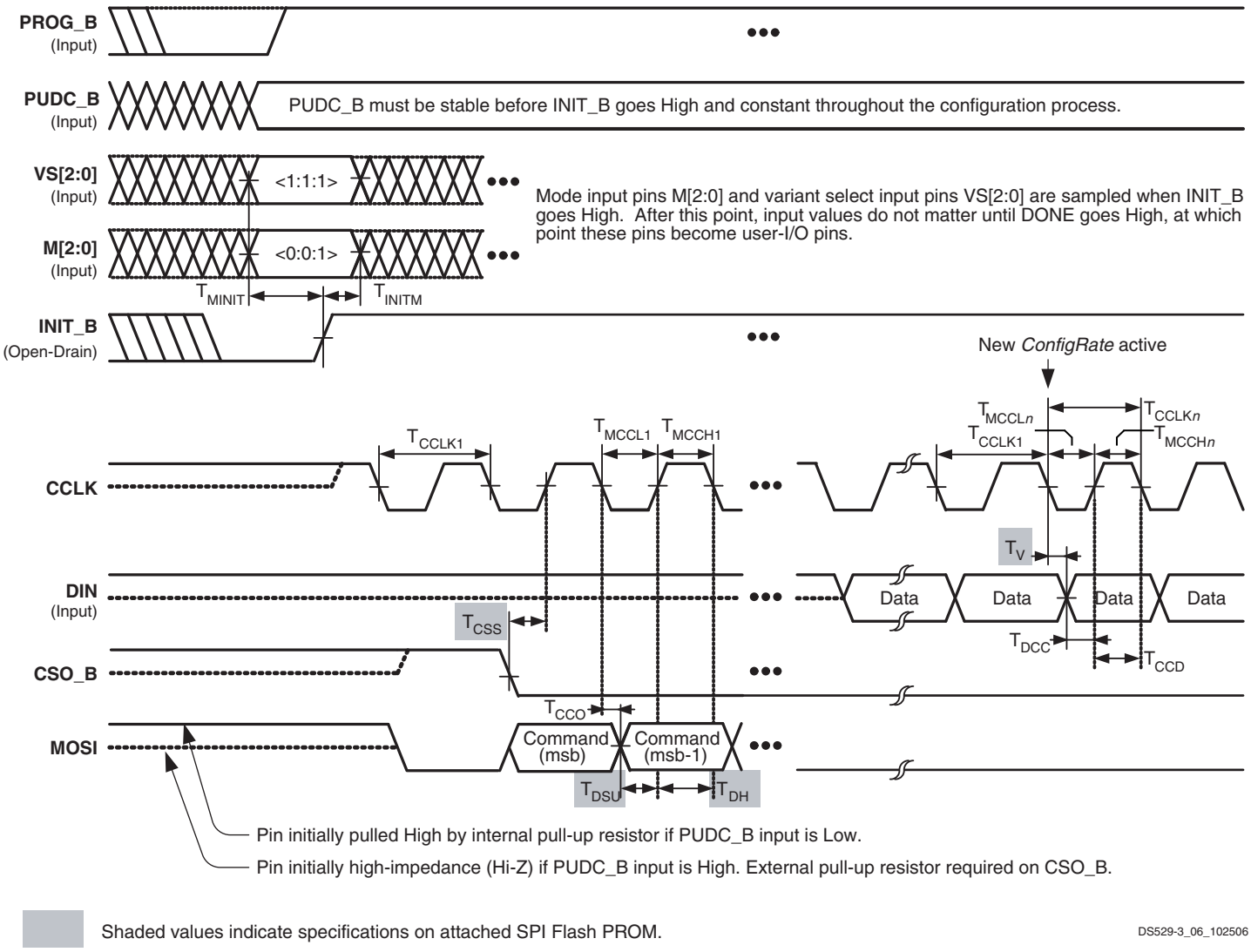


Figure 16: **Waveforms for External Serial Peripheral Interface (SPI) Configuration**

Table 57: **Timing for External Serial Peripheral Interface (SPI) Configuration Mode**

Symbol	Description	Minimum	Maximum	Units
T_{CCLK1}	Initial CCLK clock period	See Table 51		
T_{CCLKn}	CCLK clock period after FPGA loads ***ConfigRate*** bitstream option setting	See Table 51		
T_{MINIT}	Setup time on VS[2:0] variant-select pins and M[2:0] mode pins before the rising edge of INIT_B	50	–	ns
T_{INITM}	Hold time on VS[2:0] variant-select pins and M[2:0] mode pins after the rising edge of INIT_B	0	–	ns
T_{CCO}	MOSI output valid delay after CCLK falling clock edge	See Table 55		
T_{DCC}	Setup time on the DIN data input before CCLK rising clock edge	See Table 55		
T_{CCD}	Hold time on the DIN data input after CCLK rising clock edge	See Table 55		

Table 61: **Timing for the JTAG[2] Test Access Port**

Symbol	Description		All Speed Grades		Units
			Min	Max	
Clock-to-Output Times					
T_{TCKTDO}	The time from the falling transition on the TCK pin to data appearing at the TDO pin		1.0	11.0	ns
Setup Times					
T_{TDITCK}	The time from the setup of data at the TDI pin to the rising transition at the TCK pin	All devices and functions except those shown below	7.0	–	ns
		Boundary-Scan commands (INTEST, EXTEST, SAMPLE) on XC3S700AN and XC3S1400AN FPGAs	11.0		
T_{TMSTCK}	The time from the setup of a logic level at the TMS pin to the rising transition at the TCK pin		7.0	–	ns
Hold Times					
T_{TCKTDI}	The time from the rising transition at the TCK pin to the point when data is last held at the TDI pin	All functions except those shown below	0	–	ns
		Configuration commands (CFG_IN, ISC_PROGRAM)	2.0		
T_{TCKTMS}	The time from the rising transition at the TCK pin to the point when a logic level is last held at the TMS pin		0	–	ns
Clock Timing					
T_{CCH}	The High pulse width at the TCK pin	All functions except ISC_DNA command	5	–	ns
T_{CCL}	The Low pulse width at the TCK pin		5	–	ns
T_{CCHDNA}	The High pulse width at the TCK pin	During ISC_DNA command	10	10,000	ns
T_{CCLDNA}	The Low pulse width at the TCK pin		10	10,000	ns
F_{TCK}	Frequency of the TCK signal	All operations on XC3S50AN, XC3S200AN, and XC3S400AN FPGAs and for BYPASS or HIGHZ instructions on all FPGAs	0	33	MHz
		All operations on XC3S700AN and XC3S1400AN FPGAs, except for BYPASS or HIGHZ instructions		20	

Notes:

1. The numbers in this table are based on the operating conditions set forth in Table 10.
2. For details on JTAG, see Chapter 9, “JTAG Configuration Mode and Boundary-Scan” in UG332 *Spartan-3 Generation Configuration User Guide*.

TQG144 Footprint

Note: Pin 1 indicator in top-left corner and logo orientation.

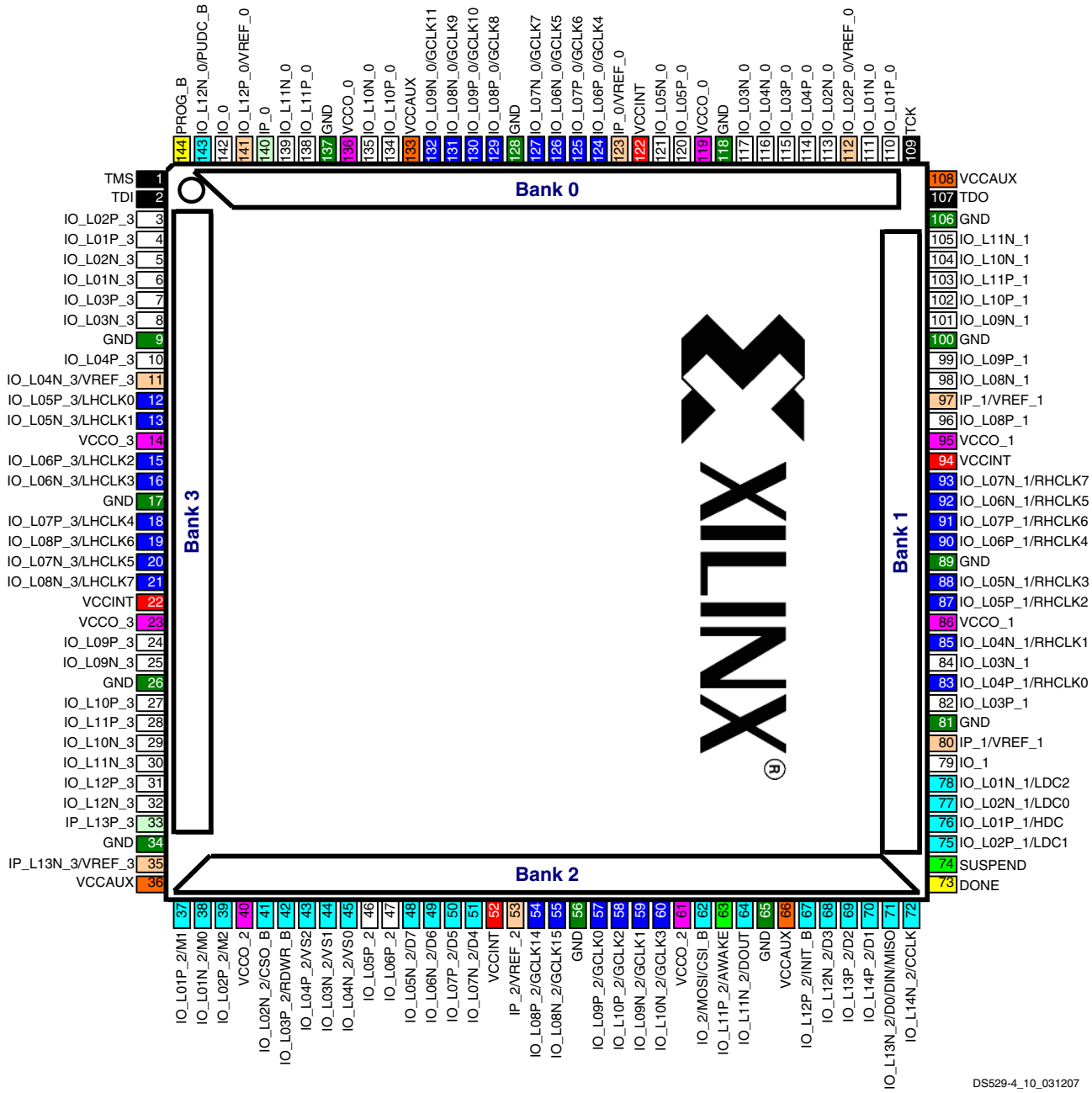


Figure 19: **XC3S50AN FPGA in TQG144 Package Footprint (Top View)**

42	**I/O:** Unrestricted, general-purpose user I/O	25	**DUAL:** Configuration pins, then possible user I/O	8	**VREF:** User I/O or input voltage reference for bank
2	**INPUT:** Unrestricted, general-purpose input pin	30	**CLK:** User I/O, input, or global buffer input	8	**VCCO:** Output voltage supply for bank
2	**CONFIG:** Dedicated configuration pins	4	**JTAG:** Dedicated JTAG port pins	4	**VCCINT:** Internal core supply voltage (+1.2V)
0	**N.C.:** Not connected	13	**GND:** Ground	4	**VCCAUX:** Auxiliary supply voltage
2	**SUSPEND:** Dedicated SUSPEND and dual-purpose AWAKE Power Management pins				

Footprint Migration Differences

Unconnected Balls on XC3S50AN

Table 73 summarizes any footprint and functionality differences between the XC3S50AN and the XC3S200AN or XC3S400AN devices for migration between these devices in the FTG256 package. The XC3S200AN and XC3S400AN have identical pinouts. The XC3S50AN pinout is compatible with the XC3S200AN and XC3S400AN, however, there are 51 unconnected balls and one functionally different ball. Generally, designs migrate upward from the XC3S50AN to either the XC3S200AN or XC3S400AN. If using differential I/O, see Table 74. If using the BPI configuration mode (parallel Flash), see Table 75.

In Table 73, the arrow (→) indicates that this pin can unconditionally migrate from the device on the left to the device on the right. Migration in the other direction is possible depending on how the pin is configured for the device on the right.

Table 73: **FTG256 XC3S50AN Footprint Migration/Differences**

FTG256 Ball	Bank	XC3S50AN	Migration	XC3S200AN or XC3S400AN
A7	0	N.C.	→	I/O
A12	0	N.C.	→	I/O
B12	0	INPUT	→	I/O
C7	0	N.C.	→	I/O
D10	0	N.C.	→	I/O
E2	3	N.C.	→	I/O
E3	3	N.C.	→	I/O
E7	0	N.C.	→	I/O/VREF
E10	0	N.C.	→	I/O/VREF
E16	1	N.C.	→	I/O
F3	3	N.C.	→	I/O
F8	0	N.C.	→	I/O
F14	1	N.C.	→	I/O
F15	1	N.C.	→	I/O
F16	1	N.C.	→	I/O
G3	3	N.C.	→	I/O
G4	3	N.C.	→	I/O
G5	3	N.C.	→	INPUT/VREF
G6	3	N.C.	→	INPUT
G13	1	N.C.	→	I/O
G14	1	N.C.	→	I/O
G16	1	N.C.	→	I/O
H4	3	N.C.	→	I/O
H5	3	N.C.	→	I/O
H6	3	N.C.	→	I/O
H13	1	N.C.	→	I/O
J4	3	N.C.	→	I/O
J6	3	N.C.	→	I/O
J10	1	N.C.	→	INPUT/VREF
J11	1	N.C.	→	INPUT
K4	3	N.C.	→	I/O

FTG256 Footprint (XC3S50AN)

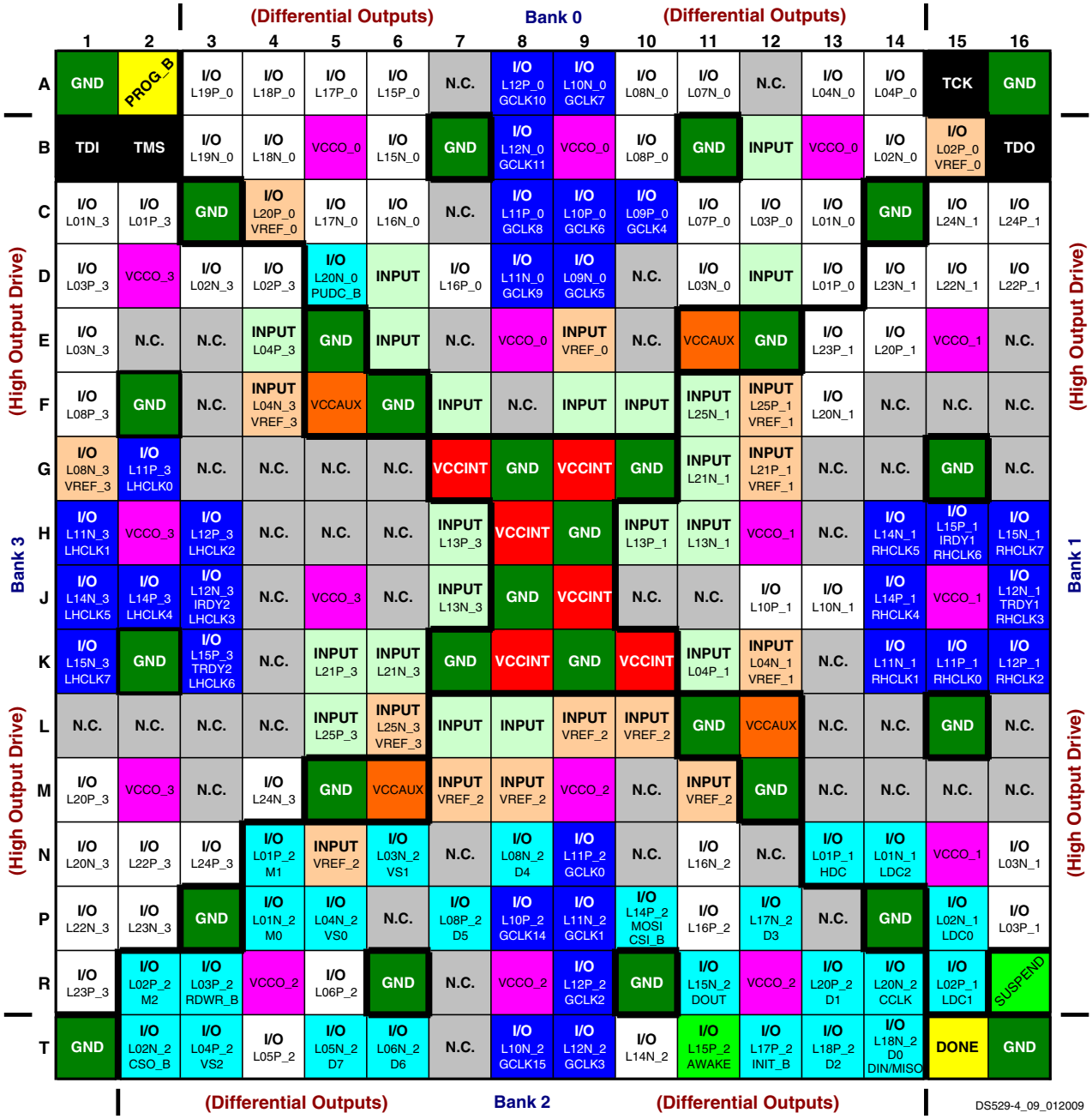


Figure 20: **XC3S50AN FTG256 Package Footprint (Top View)**

53	**I/O:** Unrestricted, general-purpose user I/O	25	**DUAL:** Configuration pins, then possible user I/O	15	**VREF:** User I/O or input voltage reference for bank	2	**SUSPEND:** Dedicated SUSPEND and dual-purpose AWAKE Power Management pins
20	**INPUT:** Unrestricted, general-purpose input pin	30	**CLK:** User I/O, input, or global buffer input	16	**VCCO:** Output voltage supply for bank		
2	**CONFIG:** Dedicated configuration pins	4	**JTAG:** Dedicated JTAG port pins	6	**VCCINT:** Internal core supply voltage (+1.2V)		
51	**N.C.:** Not connected (XC3S50AN only)	28	**GND:** Ground	4	**VCCAUX:** Auxiliary supply voltage		

FGG400: 400-Ball Fine-Pitch Ball Grid Array

The 400-ball fine-pitch ball grid array, FGG400, supports the XC3S400AN FPGA as shown in Table 76 and Figure 22.

Table 76 lists all the FGG400 package pins. They are sorted by bank number and then by pin name. Pins that form a differential I/O pair appear together in the table. The table also shows the pin number for each pin and the pin type (as defined in Table 62).

An electronic version of this package pinout table and footprint diagram is available for download from the Xilinx website at: www.xilinx.com/support/documentation/data_sheets/s3a_pin.zip.

Pinout Table

Table 76: **Spartan-3AN FGG400 Pinout**

Bank	Pin Name	FGG400 Ball	Type
0	IO_L01N_0	A18	I/O
0	IO_L01P_0	B18	I/O
0	IO_L02N_0	C17	I/O
0	IO_L02P_0/VREF_0	D17	VREF
0	IO_L03N_0	E15	I/O
0	IO_L03P_0	D16	I/O
0	IO_L04N_0	A17	I/O
0	IO_L04P_0/VREF_0	B17	VREF
0	IO_L05N_0	A16	I/O
0	IO_L05P_0	C16	I/O
0	IO_L06N_0	C15	I/O
0	IO_L06P_0	D15	I/O
0	IO_L07N_0	A14	I/O
0	IO_L07P_0	C14	I/O
0	IO_L08N_0	A15	I/O
0	IO_L08P_0	B15	I/O
0	IO_L09N_0	F13	I/O
0	IO_L09P_0	E13	I/O
0	IO_L10N_0/VREF_0	C13	VREF
0	IO_L10P_0	D14	I/O
0	IO_L11N_0	C12	I/O
0	IO_L11P_0	B13	I/O
0	IO_L12N_0	F12	I/O
0	IO_L12P_0	D12	I/O
0	IO_L13N_0	A12	I/O
0	IO_L13P_0	B12	I/O
0	IO_L14N_0	C11	I/O
0	IO_L14P_0	B11	I/O
0	IO_L15N_0/GCLK5	E11	GCLK
0	IO_L15P_0/GCLK4	D11	GCLK
0	IO_L16N_0/GCLK7	C10	GCLK

Table 76: **Spartan-3AN FGG400 Pinout *(Cont'd)***

Bank	Pin Name	FGG400 Ball	Type
0	IO_L16P_0/GCLK6	A10	GCLK
0	IO_L17N_0/GCLK9	E10	GCLK
0	IO_L17P_0/GCLK8	D10	GCLK
0	IO_L18N_0/GCLK11	A8	GCLK
0	IO_L18P_0/GCLK10	A9	GCLK
0	IO_L19N_0	C9	I/O
0	IO_L19P_0	B9	I/O
0	IO_L20N_0	C8	I/O
0	IO_L20P_0	B8	I/O
0	IO_L21N_0	D8	I/O
0	IO_L21P_0	C7	I/O
0	IO_L22N_0/VREF_0	F9	VREF
0	IO_L22P_0	E9	I/O
0	IO_L23N_0	F8	I/O
0	IO_L23P_0	E8	I/O
0	IO_L24N_0	A7	I/O
0	IO_L24P_0	B7	I/O
0	IO_L25N_0	C6	I/O
0	IO_L25P_0	A6	I/O
0	IO_L26N_0	B5	I/O
0	IO_L26P_0	A5	I/O
0	IO_L27N_0	F7	I/O
0	IO_L27P_0	E7	I/O
0	IO_L28N_0	D6	I/O
0	IO_L28P_0	C5	I/O
0	IO_L29N_0	C4	I/O
0	IO_L29P_0	A4	I/O
0	IO_L30N_0	B3	I/O
0	IO_L30P_0	A3	I/O
0	IO_L31N_0	F6	I/O
0	IO_L31P_0	E6	I/O

Table 82: **Spartan-3AN FGG676 Pinout *(Cont'd)***

Bank	Pin Name	FGG676 Ball	Type
0	IO_L33N_0	B10	I/O
0	IO_L33P_0	A10	I/O
0	IO_L34N_0	D10	I/O
0	IO_L34P_0	C10	I/O
0	IO_L35N_0	H12	I/O
0	IO_L35P_0	G12	I/O
0	IO_L36N_0	B9	I/O
0	IO_L36P_0	A9	I/O
0	IO_L37N_0	D9	I/O
0	IO_L37P_0	E10	I/O
0	IO_L38N_0	B8	I/O
0	IO_L38P_0	A8	I/O
0	IO_L39N_0	K12	I/O
0	IO_L39P_0	J12	I/O
0	IO_L40N_0	D8	I/O
0	IO_L40P_0	C8	I/O
0	IO_L41N_0	C6	I/O
0	IO_L41P_0	B6	I/O
0	IO_L42N_0	C7	I/O
0	IO_L42P_0	B7	I/O
0	IO_L43N_0	K11	I/O
0	IO_L43P_0	J11	I/O
0	IO_L44N_0	D6	I/O
0	IO_L44P_0	C5	I/O
0	IO_L45N_0	B4	I/O
0	IO_L45P_0	A4	I/O
0	IO_L46N_0	H10	I/O
0	IO_L46P_0	G10	I/O
0	IO_L47N_0	H9	I/O
0	IO_L47P_0	G9	I/O
0	IO_L48N_0	E7	I/O
0	IO_L48P_0	F7	I/O
0	IO_L51N_0	B3	I/O
0	IO_L51P_0	A3	I/O
0	IO_L52N_0/PUDC_B	G8	DUAL
0	IO_L52P_0/VREF_0	F8	VREF
0	IP_0	A5	INPUT
0	IP_0	A7	INPUT
0	IP_0	A13	INPUT
0	IP_0	A17	INPUT

Table 82: **Spartan-3AN FGG676 Pinout *(Cont'd)***

Bank	Pin Name	FGG676 Ball	Type
0	IP_0	A23	INPUT
0	IP_0	C4	INPUT
0	IP_0	D12	INPUT
0	IP_0	D15	INPUT
0	IP_0	D19	INPUT
0	IP_0	E11	INPUT
0	IP_0	E18	INPUT
0	IP_0	E20	INPUT
0	IP_0	F10	INPUT
0	IP_0	G14	INPUT
0	IP_0	G16	INPUT
0	IP_0	H13	INPUT
0	IP_0	H18	INPUT
0	IP_0	J10	INPUT
0	IP_0	J13	INPUT
0	IP_0	J15	INPUT
0	IP_0/VREF_0	D7	VREF
0	IP_0/VREF_0	D14	VREF
0	IP_0/VREF_0	G11	VREF
0	IP_0/VREF_0	J17	VREF
0	N.C.	A24	N.C.
0	N.C.	B24	N.C.
0	N.C.	D5	N.C.
0	N.C.	E9	N.C.
0	N.C.	F18	N.C.
0	N.C.	E6	N.C.
0	N.C.	F9	N.C.
0	N.C.	G18	N.C.
0	VCCO_0	B5	VCCO
0	VCCO_0	B11	VCCO
0	VCCO_0	B16	VCCO
0	VCCO_0	B22	VCCO
0	VCCO_0	E8	VCCO
0	VCCO_0	E13	VCCO
0	VCCO_0	E19	VCCO
0	VCCO_0	H11	VCCO
0	VCCO_0	H16	VCCO
1	IO_L01N_1/LDC2	Y21	DUAL
1	IO_L01P_1/HDC	Y20	DUAL
1	IO_L02N_1/LDC0	AD25	DUAL

Table 82: **Spartan-3AN FGG676 Pinout *(Cont'd)***

Bank	Pin Name	FGG676 Ball	Type
1	IO_L02P_1/LDC1	AE26	DUAL
1	IO_L03N_1/A1	AC24	DUAL
1	IO_L03P_1/A0	AC23	DUAL
1	IO_L04N_1	W21	I/O
1	IO_L04P_1	W20	I/O
1	IO_L05N_1	AC25	I/O
1	IO_L05P_1	AD26	I/O
1	IO_L06N_1	AB26	I/O
1	IO_L06P_1	AC26	I/O
1	IO_L07N_1/VREF_1	AB24	VREF
1	IO_L07P_1	AB23	I/O
1	IO_L08N_1	V19	I/O
1	IO_L08P_1	V18	I/O
1	IO_L09N_1	AA23	I/O
1	IO_L09P_1	AA22	I/O
1	IO_L10N_1	U20	I/O
1	IO_L10P_1	V21	I/O
1	IO_L11N_1	AA25	I/O
1	IO_L11P_1	AA24	I/O
1	IO_L12N_1	U18	I/O
1	IO_L12P_1	U19	I/O
1	IO_L13N_1	Y23	I/O
1	IO_L13P_1	Y22	I/O
1	IO_L14N_1	T20	I/O
1	IO_L14P_1	U21	I/O
1	IO_L15N_1	Y25	I/O
1	IO_L15P_1	Y24	I/O
1	IO_L17N_1	T17	I/O
1	IO_L17P_1	T18	I/O
1	IO_L18N_1	V22	I/O
1	IO_L18P_1	W23	I/O
1	IO_L19N_1	V25	I/O
1	IO_L19P_1	V24	I/O
1	IO_L21N_1	U22	I/O
1	IO_L21P_1	V23	I/O
1	IO_L22N_1	R20	I/O
1	IO_L22P_1	R19	I/O
1	IO_L23N_1/VREF_1	U24	VREF
1	IO_L23P_1	U23	I/O
1	IO_L25N_1/A3	R22	DUAL

Table 82: **Spartan-3AN FGG676 Pinout *(Cont'd)***

Bank	Pin Name	FGG676 Ball	Type
1	IO_L25P_1/A2	R21	DUAL
1	IO_L26N_1/A5	T24	DUAL
1	IO_L26P_1/A4	T23	DUAL
1	IO_L27N_1/A7	R17	DUAL
1	IO_L27P_1/A6	R18	DUAL
1	IO_L29N_1/A9	R26	DUAL
1	IO_L29P_1/A8	R25	DUAL
1	IO_L30N_1/RHCLK1	P20	RHCLK
1	IO_L30P_1/RHCLK0	P21	RHCLK
1	IO_L31N_1/TRDY1/RHCLK3	P25	RHCLK
1	IO_L31P_1/RHCLK2	P26	RHCLK
1	IO_L33N_1/RHCLK5	N24	RHCLK
1	IO_L33P_1/RHCLK4	P23	RHCLK
1	IO_L34N_1/RHCLK7	N19	RHCLK
1	IO_L34P_1/IRDY1/RHCLK6	P18	RHCLK
1	IO_L35N_1/A11	M25	DUAL
1	IO_L35P_1/A10	M26	DUAL
1	IO_L37N_1	N21	I/O
1	IO_L37P_1	P22	I/O
1	IO_L38N_1/A13	M23	DUAL
1	IO_L38P_1/A12	L24	DUAL
1	IO_L39N_1/A15	N17	DUAL
1	IO_L39P_1/A14	N18	DUAL
1	IO_L41N_1	K26	I/O
1	IO_L41P_1	K25	I/O
1	IO_L42N_1/A17	M20	DUAL
1	IO_L42P_1/A16	N20	DUAL
1	IO_L43N_1/A19	J25	DUAL
1	IO_L43P_1/A18	J26	DUAL
1	IO_L45N_1	M22	I/O
1	IO_L45P_1	M21	I/O
1	IO_L46N_1	K22	I/O
1	IO_L46P_1	K23	I/O
1	IO_L47N_1	M18	I/O
1	IO_L47P_1	M19	I/O
1	IO_L49N_1	J22	I/O
1	IO_L49P_1	J23	I/O
1	IO_L50N_1	K21	I/O
1	IO_L50P_1	L22	I/O
1	IO_L51N_1	G24	I/O

Table 82: **Spartan-3AN FGG676 Pinout *(Cont'd)***

Bank	Pin Name	FGG676 Ball	Type
3	IP_L58N_3/VREF_3	AA5	VREF
3	IP_L58P_3	AA4	INPUT
3	IP_L62N_3	AB4	INPUT
3	IP_L62P_3	AB3	INPUT
3	IP_L66N_3/VREF_3	AE2	VREF
3	IP_L66P_3	AE1	INPUT
3	VCCO_3	AB2	VCCO
3	VCCO_3	E2	VCCO
3	VCCO_3	H5	VCCO
3	VCCO_3	L2	VCCO
3	VCCO_3	L8	VCCO
3	VCCO_3	P5	VCCO
3	VCCO_3	T2	VCCO
3	VCCO_3	T8	VCCO
3	VCCO_3	W5	VCCO
GND	GND	A1	GND
GND	GND	A6	GND
GND	GND	A11	GND
GND	GND	A16	GND
GND	GND	A21	GND
GND	GND	A26	GND
GND	GND	AA1	GND
GND	GND	AA6	GND
GND	GND	AA11	GND
GND	GND	AA16	GND
GND	GND	AA21	GND
GND	GND	AA26	GND
GND	GND	AD3	GND
GND	GND	AD8	GND
GND	GND	AD13	GND
GND	GND	AD18	GND
GND	GND	AD24	GND
GND	GND	AF1	GND
GND	GND	AF6	GND
GND	GND	AF11	GND
GND	GND	AF16	GND
GND	GND	AF21	GND
GND	GND	AF26	GND
GND	GND	C3	GND
GND	GND	C9	GND

Table 82: **Spartan-3AN FGG676 Pinout *(Cont'd)***

Bank	Pin Name	FGG676 Ball	Type
GND	GND	C14	GND
GND	GND	C19	GND
GND	GND	C24	GND
GND	GND	F1	GND
GND	GND	F6	GND
GND	GND	F11	GND
GND	GND	F16	GND
GND	GND	F21	GND
GND	GND	F26	GND
GND	GND	H3	GND
GND	GND	H8	GND
GND	GND	H14	GND
GND	GND	H19	GND
GND	GND	J24	GND
GND	GND	K10	GND
GND	GND	K17	GND
GND	GND	L1	GND
GND	GND	L6	GND
GND	GND	L11	GND
GND	GND	L13	GND
GND	GND	L15	GND
GND	GND	L21	GND
GND	GND	L26	GND
GND	GND	M12	GND
GND	GND	M14	GND
GND	GND	M16	GND
GND	GND	N3	GND
GND	GND	N8	GND
GND	GND	N11	GND
GND	GND	N15	GND
GND	GND	P12	GND
GND	GND	P16	GND
GND	GND	P19	GND
GND	GND	P24	GND
GND	GND	R11	GND
GND	GND	R13	GND
GND	GND	R15	GND
GND	GND	T1	GND
GND	GND	T6	GND
GND	GND	T12	GND

Notice of Disclaimer